

PATENT

Docket No.:JCLA8533-D2

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of :

Applicant : MOU-SHIUNG LIN et al.

Filed : Herewith

For : INTEGRATED CHIP PACKAGE STRUCTURE USING
SILICON SUBSTRATE AND METHOD OF MANUFACTURING
THE SAME

PRELIMINARY AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Prior to the examination on merits, please amend the above-identified application as shown in the attached sheets. No new matter has added through the amendment. Entry of the amendment is requested.